



MICROCHIP

QUALIFICATION PLAN

PCN #: JAON-15OELO113

Date:
March 9, 2016

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K, 160K and 250K wafer technologies available in 8L MSOP package at MTAI assembly site.

Distribution

Surasit P.
A. Navarro
Wichai K.
Chaweng W.
Chalermpon P.
Atthapong W.

Greg P.
Vassilis D.
Fernando C.
Gerry O.
Arnel M.
Sombat K.

Microchip Technology (Thailand) Co., Ltd.
14 Moo 1 T. Wangtakien A. Muangchacherngsao,
Chacherngsao, Thailand, 24000
Tel. (6638) 857119-45, 857311-19 ext. 1231
Fax (6638) 857149-50

Purpose: _____ Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K, 160K and 250K wafer technologies available in 8L MSOP package at MTAI assembly site.

CCB No.: _____ 2594

<u>Misc.</u>	Assembly site	MTAI
	BD Number	BDM-001031 rev.A
	MP Code (MPC)	D5AJ5TA3XB00
	Part Number (CPN)	25AA080CT-I/MS
<u>Lead-Frame</u>	Paddle size	82x94 mils
	Material	CDA194
	Surface	Bare Cu DAP
	Treatment	Brown Oxide Treated
	Process	Stamped
	Lead-lock	No
	Lead Plating	Matte Tin
<u>Bond Wire</u>	Material	CuPdAu
<u>Die Attach</u>	Part Number	8390A
	Conductive	Yes
<u>MC</u>	Part Number	G600V
<u>PKG</u>	PKG Type	MSOP
	Pin/Ball Count	8
	PKG width/size	3x3 mm
<u>Die</u>	Die Thickness	8 mils
	Die Size	66.4 x 52.8 mils

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	3	24	0 fails after TC	5	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	3	24	0	5	30 bonds from a minimum of 5 devices.
Wire Sweep		5	0	3	15	0		Required for any reduction in wire bond thickness.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25°C and hot temp 85°C.	45	5	1	50	0	10	Must be in progress at time of package release to production, but completion is not required for release to production.
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type; Electrical test pre and post stress at +25°C. MSL1 @ 260°C	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp 85°C.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	+130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp 85°C; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
24AA01-I/MS
24AA01T-I/MS
24AA02-I/MS
24AA02T-I/MS
24AA044-E/MS
24AA044-I/MS
24AA044T-E/MS
24AA044T-I/MS
24AA04H-I/MS
24AA04HT-I/MS
24AA04-I/MS
24AA04T-I/MS
24AA08H-I/MS
24AA08HT-I/MS
24AA08-I/MS
24AA08T-I/MS
24AA128-I/MS
24AA128T-I/MS
24AA16-E/MS
24AA16H-I/MS
24AA16HT-I/MS
24AA16-I/MS
24AA16T-E/MS
24AA16T-I/MS
24AA256-E/MS
24AA256-I/MS
24AA256-I/MSRVE
24AA256T-E/MS
24AA256T-I/MS
24AA256T-I/MSRVE
24AA32AF-I/MS
24AA32AFT-I/MS
24AA32A-I/MS
24AA32AT-I/MS
24AA64-E/MS
24AA64F-I/MS
24AA64FT-I/MS
24AA64-I/MS
24AA64T-E/MS
24AA64T-I/MS
24FC128-I/MS
24FC128T-I/MS
24FC256-I/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
24FC256T-I/MS
24FC64F-I/MS
24FC64FT-I/MS
24FC64-I/MS
24FC64T-I/MS
24LC01B-I/MS
24LC01BT-I/MS
24LC02B-E/MS
24LC02B-I/MS
24LC02BT-E/MS
24LC02BT-I/MS
24LC04B-E/MS
24LC04BH-E/MS
24LC04BH-I/MS
24LC04BHT-E/MS
24LC04BHT-I/MS
24LC04B-I/MS
24LC04BT-E/MS
24LC04BT-I/MS
24LC08B-E/MS
24LC08BH-E/MS
24LC08BH-I/MS
24LC08BHT-E/MS
24LC08BHT-I/MS
24LC08B-I/MS
24LC08BT-E/MS
24LC08BT-I/MS
24LC128-E/MS
24LC128-I/MS
24LC128T-E/MS
24LC128T-I/MS
24LC16B-E/MS
24LC16BH-E/MS
24LC16BH-I/MS
24LC16BHT-E/MS
24LC16BHT-I/MS
24LC16B-I/MS
24LC16BT-E/MS
24LC16BT-I/MS
24LC256-E/MS
24LC256-I/MS
24LC256-I/MSRVF
24LC256T-E/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
24LC256T-I/MS
24LC256T-I/MSRVF
24LC32A-E/MS
24LC32AF-E/MS
24LC32AF-I/MS
24LC32AFT-E/MS
24LC32AFT-I/MS
24LC32A-I/MS
24LC32AT-E/MS
24LC32AT-I/MS
24LC64-E/MS
24LC64F-E/MS
24LC64F-I/MS
24LC64FT-E/MS
24LC64FT-I/MS
24LC64-I/MS
24LC64T-E/MS
24LC64T-I/MS
25AA010A-I/MS
25AA010AT-I/MS
25AA020A-I/MS
25AA020AT-I/MS
25AA040A-I/MS
25AA040AT-I/MS
25AA080A-I/MS
25AA080AT-I/MS
25AA080B-I/MS
25AA080BT-I/MS
25AA080C-I/MS
25AA080CT-I/MS
25AA080D-I/MS
25AA080DT-I/MS
25AA160A-I/MS
25AA160AT-I/MS
25AA160B-I/MS
25AA160BT-I/MS
25AA160C-I/MS
25AA160CT-I/MS
25AA160D-E/MS
25AA160D-I/MS
25AA160DT-E/MS
25AA160DT-I/MS
25AA320A-I/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
25AA320AT-I/MS
25AA640A-E/MS
25AA640A-I/MS
25AA640AT-E/MS
25AA640AT-I/MS
25LC010A-E/MS
25LC010A-I/MS
25LC010AT-E/MS
25LC010AT-I/MS
25LC020A-E/MS
25LC020A-I/MS
25LC020AT-E/MS
25LC020AT-I/MS
25LC040A-E/MS
25LC040A-I/MS
25LC040AT-E/MS
25LC040AT-I/MS
25LC080A-E/MS
25LC080A-I/MS
25LC080AT-E/MS
25LC080AT-I/MS
25LC080B-E/MS
25LC080B-I/MS
25LC080BT-E/MS
25LC080BT-I/MS
25LC080C-E/MS
25LC080C-I/MS
25LC080CT-E/MS
25LC080CT-I/MS
25LC080D-E/MS
25LC080D-I/MS
25LC080DT-E/MS
25LC080DT-I/MS
25LC160A-E/MS
25LC160A-I/MS
25LC160AT-E/MS
25LC160AT-I/MS
25LC160B-E/MS
25LC160B-I/MS
25LC160BT-E/MS
25LC160BT-I/MS
25LC160C-E/MS
25LC160C-I/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
25LC160CT-E/MS
25LC160CT-I/MS
25LC160D-E/MS
25LC160D-I/MS
25LC160DT-E/MS
25LC160DT-I/MS
25LC320A-E/MS
25LC320A-I/MS
25LC320AT-E/MS
25LC320AT-I/MS
25LC640A-E/MS
25LC640A-I/MS
25LC640AT-E/MS
25LC640AT-I/MS
93AA46A-I/MS
93AA46AT-I/MS
93AA46B-I/MS
93AA46BT-I/MS
93AA46C-I/MS
93AA46CT-I/MS
93AA56A-I/MS
93AA56AT-I/MS
93AA56B-I/MS
93AA56BT-I/MS
93AA56C-I/MS
93AA56CT-I/MS
93AA66A-I/MS
93AA66AT-I/MS
93AA66B-I/MS
93AA66B-I/MSL21
93AA66BT-I/MS
93AA66BT-I/MSL21
93AA66C-I/MS
93AA66CT-I/MS
93AA76A-I/MS
93AA76AT-I/MS
93AA76B-I/MS
93AA76BT-I/MS
93AA76C-I/MS
93AA76CT-I/MS
93AA86A-I/MS
93AA86AT-I/MS
93AA86B-I/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
93AA86BT-I/MS
93AA86C-I/MS
93AA86CT-I/MS
93C46A-E/MS
93C46A-I/MS
93C46AT-E/MS
93C46AT-I/MS
93C46B-E/MS
93C46B-I/MS
93C46BT-E/MS
93C46BT-I/MS
93C46C-E/MS
93C46C-I/MS
93C46CT-E/MS
93C46CT-I/MS
93C56A-E/MS
93C56A-I/MS
93C56AT-E/MS
93C56AT-I/MS
93C56B-E/MS
93C56B-I/MS
93C56BT-E/MS
93C56BT-I/MS
93C56C-E/MS
93C56C-I/MS
93C56CT-E/MS
93C56CT-I/MS
93C66A-E/MS
93C66A-I/MS
93C66AT-E/MS
93C66AT-I/MS
93C66B-E/MS
93C66B-I/MS
93C66BT-E/MS
93C66BT-I/MS
93C66C-E/MS
93C66C-I/MS
93C66CT-E/MS
93C66CT-I/MS
93C76A-E/MS
93C76A-I/MS
93C76AT-E/MS
93C76AT-I/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
93C76B-E/MS
93C76B-I/MS
93C76BT-E/MS
93C76BT-I/MS
93C76C-E/MS
93C76C-I/MS
93C76CT-E/MS
93C76CT-I/MS
93C86A-E/MS
93C86A-I/MS
93C86AT-E/MS
93C86AT-I/MS
93C86B-E/MS
93C86B-I/MS
93C86BT-E/MS
93C86BT-I/MS
93C86C-E/MS
93C86C-I/MS
93C86CT-E/MS
93C86CT-I/MS
93LC46A-E/MS
93LC46A-I/MS
93LC46AT-E/MS
93LC46AT-I/MS
93LC46B-E/MS
93LC46B-I/MS
93LC46BT-E/MS
93LC46BT-I/MS
93LC46C-E/MS
93LC46C-I/MS
93LC46CT-E/MS
93LC46CT-I/MS
93LC56A-E/MS
93LC56A-I/MS
93LC56AT-E/MS
93LC56AT-I/MS
93LC56B-E/MS
93LC56B-I/MS
93LC56BT-E/MS
93LC56BT-I/MS
93LC56C-E/MS
93LC56C-I/MS
93LC56CT-E/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
93LC56CT-I/MS
93LC66A-E/MS
93LC66A-I/MS
93LC66AT-E/MS
93LC66AT-I/MS
93LC66B-E/MS
93LC66B-I/MS
93LC66BT-E/MS
93LC66BT-I/MS
93LC66C-E/MS
93LC66C-I/MS
93LC66CT-E/MS
93LC66CT-I/MS
93LC76A-E/MS
93LC76A-I/MS
93LC76AT-E/MS
93LC76AT-I/MS
93LC76B-E/MS
93LC76B-I/MS
93LC76BT-E/MS
93LC76BT-I/MS
93LC76C-E/MS
93LC76C-I/MS
93LC76CT-E/MS
93LC76CT-I/MS
93LC86A-E/MS
93LC86A-I/MS
93LC86AT-E/MS
93LC86AT-I/MS
93LC86B-E/MS
93LC86B-I/MS
93LC86BT-E/MS
93LC86BT-I/MS
93LC86C-E/MS
93LC86C-I/MS
93LC86CT-E/MS
93LC86CT-I/MS
MCP1632-AAE/MS
MCP1632-BAE/MS
MCP1632T-AAE/MS
MCP1632T-BAE/MS
MCP3422A0-E/MS
MCP3422A0T-E/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP3422A1-E/MS
MCP3422A1T-E/MS
MCP3422A2-E/MS
MCP3422A2T-E/MS
MCP3422A3-E/MS
MCP3422A3T-E/MS
MCP3422A4-E/MS
MCP3422A4T-E/MS
MCP3422A5-E/MS
MCP3422A5T-E/MS
MCP3422A6-E/MS
MCP3422A6T-E/MS
MCP3422A7-E/MS
MCP3422A7T-E/MS
MCP3426A0-E/MS
MCP3426A0T-E/MS
MCP3426A1-E/MS
MCP3426A1T-E/MS
MCP3426A2-E/MS
MCP3426A2T-E/MS
MCP3426A3-E/MS
MCP3426A3T-E/MS
MCP3426A4-E/MS
MCP3426A4T-E/MS
MCP3426A5-E/MS
MCP3426A5T-E/MS
MCP3426A6-E/MS
MCP3426A6T-E/MS
MCP3426A7-E/MS
MCP3426A7T-E/MS
MCP3550-50E/MS
MCP3550-60E/MS
MCP3550T-50E/MS
MCP3550T-60E/MS
MCP3551-E/MS
MCP3551T-E/MS
MCP3553-E/MS
MCP3553T-E/MS
MCP4011-103E/MS
MCP4011-202E/MS
MCP4011-502E/MS
MCP4011-503E/MS
MCP4011T-103E/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP4011T-202E/MS
MCP4011T-502E/MS
MCP4011T-503E/MS
MCP4021-103E/MS
MCP4021-202E/MS
MCP4021-502E/MS
MCP4021-503E/MS
MCP4021T-103E/MS
MCP4021T-202E/MS
MCP4021T-502E/MS
MCP4021T-503E/MS
MCP4131-103E/MS
MCP4131-104E/MS
MCP4131-502E/MS
MCP4131-503E/MS
MCP4131T-103E/MS
MCP4131T-104E/MS
MCP4131T-502E/MS
MCP4131T-503E/MS
MCP4132-103E/MS
MCP4132-104E/MS
MCP4132-502E/MS
MCP4132-503E/MS
MCP4132T-103E/MS
MCP4132T-104E/MS
MCP4132T-502E/MS
MCP4132T-503E/MS
MCP4141-103E/MS
MCP4141-104E/MS
MCP4141-502E/MS
MCP4141-503E/MS
MCP4141T-103E/MS
MCP4141T-104E/MS
MCP4141T-502E/MS
MCP4141T-503E/MS
MCP4142-103E/MS
MCP4142-104E/MS
MCP4142-502E/MS
MCP4142-503E/MS
MCP4142T-103E/MS
MCP4142T-104E/MS
MCP4142T-502E/MS
MCP4142T-503E/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP4151-103E/MS
MCP4151-104E/MS
MCP4151-502E/MS
MCP4151-503E/MS
MCP4151T-103E/MS
MCP4151T-104E/MS
MCP4151T-502E/MS
MCP4151T-503E/MS
MCP4152-103E/MS
MCP4152-104E/MS
MCP4152-502E/MS
MCP4152-503E/MS
MCP4152T-103E/MS
MCP4152T-104E/MS
MCP4152T-502E/MS
MCP4152T-503E/MS
MCP4161-103E/MS
MCP4161-104E/MS
MCP4161-502E/MS
MCP4161-503E/MS
MCP4161T-103E/MS
MCP4161T-104E/MS
MCP4161T-502E/MS
MCP4161T-503E/MS
MCP4162-103E/MS
MCP4162-104E/MS
MCP4162-502E/MS
MCP4162-503E/MS
MCP4162T-103E/MS
MCP4162T-104E/MS
MCP4162T-502E/MS
MCP4162T-503E/MS
MCP4531-103E/MS
MCP4531-104E/MS
MCP4531-502E/MS
MCP4531-503E/MS
MCP4531T-103E/MS
MCP4531T-104E/MS
MCP4531T-502E/MS
MCP4531T-503E/MS
MCP4532-103E/MS
MCP4532-104E/MS
MCP4532-502E/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP4532-503E/MS
MCP4532T-103E/MS
MCP4532T-104E/MS
MCP4532T-502E/MS
MCP4532T-503E/MS
MCP4541-103E/MS
MCP4541-104E/MS
MCP4541-502E/MS
MCP4541-503E/MS
MCP4541T-103E/MS
MCP4541T-104E/MS
MCP4541T-502E/MS
MCP4541T-503E/MS
MCP4542-103E/MS
MCP4542-104E/MS
MCP4542-502E/MS
MCP4542-503E/MS
MCP4542T-103E/MS
MCP4542T-104E/MS
MCP4542T-502E/MS
MCP4542T-503E/MS
MCP4551-103E/MS
MCP4551-104E/MS
MCP4551-502E/MS
MCP4551-503E/MS
MCP4551T-103E/MS
MCP4551T-104E/MS
MCP4551T-502E/MS
MCP4551T-503E/MS
MCP4552-103E/MS
MCP4552-104E/MS
MCP4552-502E/MS
MCP4552-503E/MS
MCP4552T-103E/MS
MCP4552T-104E/MS
MCP4552T-502E/MS
MCP4552T-503E/MS
MCP4561-103E/MS
MCP4561-104E/MS
MCP4561-502E/MS
MCP4561-503E/MS
MCP4561T-103E/MS
MCP4561T-104E/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP4561T-502E/MS
MCP4561T-503E/MS
MCP4562-103E/MS
MCP4562-104E/MS
MCP4562-502E/MS
MCP4562-503E/MS
MCP4562T-103E/MS
MCP4562T-104E/MS
MCP4562T-502E/MS
MCP4562T-503E/MS
MCP4801-E/MS
MCP4801T-E/MS
MCP4802-E/MS
MCP4802T-E/MS
MCP4811-E/MS
MCP4811T-E/MS
MCP4812-E/MS
MCP4812T-E/MS
MCP4821-E/MS
MCP4821T-E/MS
MCP4822-E/MS
MCP4822T-E/MS
MCP4901-E/MS
MCP4901T-E/MS
MCP4911-E/MS
MCP4911T-E/MS
MCP4921-E/MS
MCP4921T-E/MS
MCP6422-E/MS
MCP6422T-E/MS
MCP6472-E/MS
MCP6472T-E/MS
MCP6482-E/MS
MCP6482T-E/MS
MCP6492-E/MS
MCP6492T-E/MS
MCP6N16-001E/MS
MCP6N16-010E/MS
MCP6N16-100E/MS
MCP6N16T-001E/MS
MCP6N16T-010E/MS
MCP6N16T-100E/MS
MCP6V12-E/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
MCP6V12T-E/MS
MCP6V32-E/MS
MCP6V32T-E/MS
MCP6V62-E/MS
MCP6V62T-E/MS
MCP6V72-E/MS
MCP6V72T-E/MS
MCP6V82-E/MS
MCP6V82T-E/MS
MCP6V92-E/MS
MCP6V92T-E/MS
MCP9801-M/MS
MCP9801-M/MSRC2
MCP9801T-M/MS
MCP9801T-M/MSRC2
MCP9803-M/MS
MCP9803-M/MSRC2
MCP9803T-M/MS
MCP9803T-M/MSRC2
MCP9804-E/MS
MCP9804-E/MSBBB
MCP9804T-E/MS
MCP9804T-E/MSBBB
MCP9808-E/MS
MCP9808T-E/MS
PIC12F508-E/MS
PIC12F508-I/MS
PIC12F508T-E/MS
PIC12F508T-I/MS
PIC12F508T-I/MS054
PIC12F508T-I/MS064
PIC12F508T-I/MS076
PIC12F508T-I/MS077
PIC12F509-E/MS
PIC12F509-I/MS
PIC12F509T-E/MS
PIC12F509T-I/MS
PIC12F509T-I/MS029
PIC12F510-E/MS
PIC12F510-I/MS
PIC12F510-I/MS04
PIC12F510T-E/MS
PIC12F510T-I/MS

JAON-15OELO113 - CCB 2594 Final Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L MSOP package at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PCN_JAON-15OELO113
CATALOG_PART_NBR
PIC12F519-E/MS
PIC12F519-I/MS
PIC12F519T-I/MS
PIC12F609-E/MS
PIC12F609-I/MS
PIC12F609T-E/MS
PIC12F609T-I/MS
PIC12F615-E/MS
PIC12F615-H/MS
PIC12F615-I/MS
PIC12F615-I/MS02
PIC12F615T-E/MS
PIC12F615T-H/MS
PIC12F615T-I/MS
PIC12F615T-I/MS059
PIC12F615T-I/MS063
PIC12F615T-I/MS068
PIC12F615T-I/MS080
PIC12F617-E/MS
PIC12F617-I/MS
PIC12F617-I/MS04
PIC12F617T-E/MS
PIC12F617T-I/MS
PIC12F617T-I/MS046
PIC12F617T-I/MS056
PIC12F617T-I/MS04
PIC12HV609-E/MS
PIC12HV609-I/MS
PIC12HV609T-I/MS
PIC12HV615-E/MS
PIC12HV615-I/MS
PIC12HV615T-E/MS
PIC12HV615T-I/MS
TCN75AVUA
TCN75AVUA713